

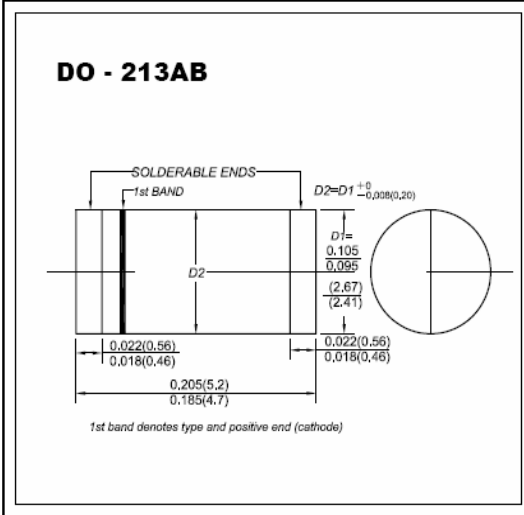
SURFACE MOUNT RECTIFIER	VOLTAGE RANGE: 50 --- 600 V CURRENT: 1.0 A
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FEATURES

- ◇ Plastic package has underwriters laboratories flammability classification 94V-0
- ◇ Glass passivated chip junction
- ◇ For surface mount applications
- ◇ High temperature metallurgically bonded construction
- ◇ Cavity-free glass passivated junction
- ◇ High temperature soldering guaranteed: 450 °C/5 seconds at terminals. Complete device submersible temperature of 265 °C for 10 seconds in solder bath

MECHANICAL DATA

- ◇ Case: JEDEC DO-213AB, molded plastic
- ◇ Terminals: Axial lead, solderable per MIL-STD-750, Method 2026
- ◇ Polarity: Color band denotes cathode
- ◇ Weight: 0.0046 ounces, 0.116 grams
- ◇ Mounting position: Any



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified.
Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%.

		GL 1A	GL 1B	GL 1D	GL 1F	GL 1G	GL 1H	GL 1J	UNITS
Maximum recurrent peak reverse voltage	V_{RRM}	50	100	200	300	400	500	600	V
Maximum RMS voltage	V_{RMS}	35	70	140	210	280	350	420	V
Maximum DC blocking voltage	V_{DC}	50	100	200	300	400	500	600	V
Maximum average forward rectified current $T_J=75^\circ\text{C}$	$I_{(AV)}$	1.0							A
Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30							A
Maximum instantaneous forward voltage @1.0A	V_F	1.25		1.35		1.70		V	
Maximum reverse current @ $T_A=25^\circ\text{C}$ at rated DC blocking voltage @ $T_A=125^\circ\text{C}$	I_R	5.0							μA
Maximum reverse recovery time (Note 1)	t_{rr}	50							ns
Typical junction capacitance (Note 2)	C_j	15							pF
Typical thermal resistance (Note 3)	$R_{\theta JA}$	150							K/W
Operating junction temperature range	T_J	- 55 ---- +175							$^\circ\text{C}$
Storage temperature range	T_{STG}	- 55 ---- +175							$^\circ\text{C}$

NOTE: 1. Measured with $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{rr}=0.25\text{A}$

2. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

3. Thermal resistance from junction to ambient, 0.24x0.24"(6.0x6.0mm) copper pads to each terminal.

FIG.1 – FORWARD CURRENT DERATING CURVE

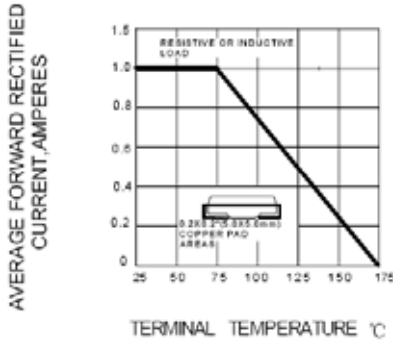


FIG.2 – MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

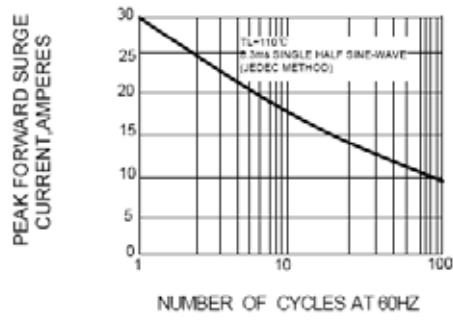


FIG.3 – TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

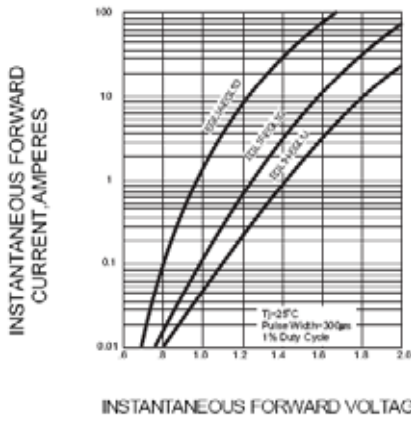


FIG.4 – TYPICAL REVERSE CHARACTERISTICS

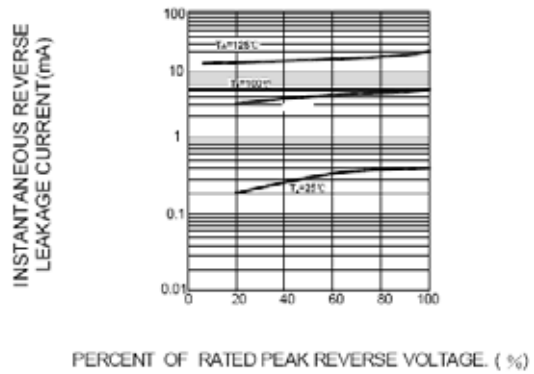


FIG.5 – TYPICAL JUNCTION CAPACITANCE

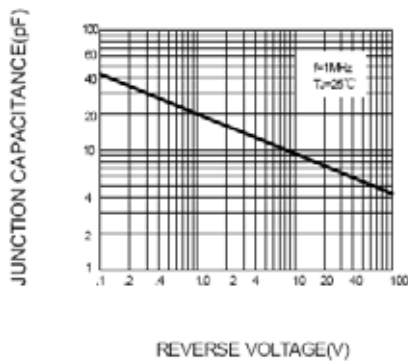
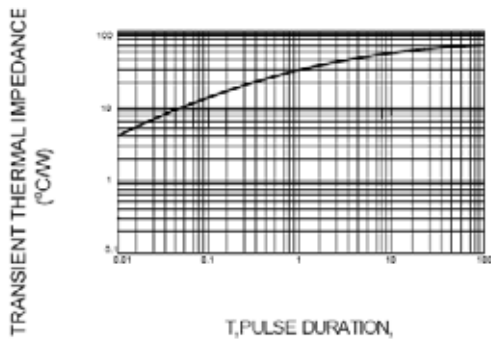


FIG.6 – TYPICAL TRANSIENT THERMAL IMPEDANCE





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